

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in this application, wherein double brackets or strikethrough font indicate deleted language and new language is underlined.

Listing of the Claims:

1. (Cancelled)

2. (Previously Presented) The probe module of claim 7, wherein each of the plurality of probe pins further comprises a probe pin head extending from the probe pin body and a generally tapered probe pin tip provided on the probe pin head.

3. (Previously Presented) The probe module of claim 7, wherein the circuit interconnect device comprises a plurality of conductive probe circuits provided on the probe base in electrical contact with the plurality of probe pins, respectively, and a flexible circuit board provided in electrical contact with the plurality of conductive probe circuits.

4. (Cancelled)

5. (Previously Presented) The probe module of claim 7, wherein each of the plurality of probe pins further comprises a probe pin head extending from the probe pin body and a generally semi-spherical probe pin tip provided on the probe pin head.

6. (Cancelled)

7. (Currently Amended) A probe module comprising:
a probe base having a plurality of conductive metal traces;
a plurality of probe pins attached to the probe base, each of the probe pins comprising an elongated body wherein at least part of the elongated body is bonded to at least one of the plurality of conductive metal traces of the probe base;

a circuit interconnect device for connecting the plurality of probe pins to an inspection apparatus;

a compression arm attached to the probe base and configured to engage the plurality of probe pins; and

at least one adjustment element provided on the probe base that adjusts the compression arm against the plurality of probe pins to adjust [[the]] a contact angle of the probe pins.

8-12. (Cancelled)

13. (Currently Amended) The probe module of claim 7 wherein the [[a]] plurality of probe pins have a generally tetrahedral probe pin tip.

14-21. (Cancelled)

22. (Previously Presented) The probe module of claim 7, wherein the flexible circuit board couples the probe pins to a testing unit via the conductive metal traces.

23. (Cancelled)

24. (Previously Presented) The probe module of claim 7, wherein the probe pins include a probe head having at least one of a tapered, semi-spherical, inverted-pyramid or a tetrahedral shape.

25. (Previously Presented) The probe module of claim 7, wherein the probe pins include an elongated arm body such that at least a part of the elongated arm body is attached with the probe base.

26-33. (Cancelled)

34. (Previously Presented) The probe module of claim 7, wherein the adjustment element is a screw.